# **Surface Mount Schottky Power Rectifier**

## **SOD-123 Power Surface Mount Package**

The Schottky Power Rectifier employs the Schottky Barrier principle with a barrier metal that produces optimal forward voltage drop—reverse current tradeoff. Ideally suited for low voltage, high frequency rectification, or as a free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package provides an alternative to the leadless 34 MELF style package.

#### **Features**

- Guardring for Stress Protection
- Very Low Forward Voltage
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- Pb-Free Packages are Available

#### **Mechanical Characteristics**

Reel Options: 3,000 per 7 inch reel/8 mm tape
Reel Options: 10,000 per 13 inch reel/8 mm tape

• Device Marking: B4

Polarity Designator: Cathode BandWeight: 11.7 mg (approximately)

• Case: Epoxy Molded

- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C max. for 10 Seconds



ON Semiconductor®

http://onsemi.com

## SCHOTTKY BARRIER RECTIFIER 0.5 AMPERES, 40 VOLTS



SOD-123 CASE 425 STYLE 1

#### **MARKING DIAGRAM**



B4 = Device Code M = Date Code

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MBR0540T1	SOD-123	3000/Tape & Reel
MBR0540T1G	SOD-123 (Pb-Free)	3000/Tape & Reel
MBR0540T3	SOD-123	10,000/Tape & Reel
MBR0540T3G	SOD-123 (Pb-Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
Average Rectified Forward Current (At Rated V <sub>R</sub> , T <sub>C</sub> = 115°C)	I <sub>O</sub>	0.5	А
Peak Repetitive Forward Current (At Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 115°C)	I <sub>FRM</sub>	1.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	IFSM	5.5	А
Storage/Operating Case Temperature Range	T <sub>stg</sub> , T <sub>C</sub>	-55 to +150	°C
Operating Junction Temperature	T <sub>J</sub>	-55 to +150	°C
Voltage Rate of Change (Rated V <sub>R</sub> , T <sub>J</sub> = 25°C)	dv/dt	1000	V/µs

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit	1
Thermal Resistance – Junction–to–Lead (Note 1)	R <sub>tjl</sub>	118	°C/W	1
Thermal Resistance – Junction–to–Ambient (Note 2)	R <sub>tja</sub>	206		l

#### **ELECTRICAL CHARACTERISTICS**

Maximum Instantaneous Forward Voltage (Note 3)	VF	T <sub>J</sub> = 25°C	T <sub>J</sub> = 100°C	V
$(i_F = 0.5 \text{ A})$ $(i_F = 1 \text{ A})$		0.51 0.62	0.46 0.61	
Maximum Instantaneous Reverse Current (Note 3)	I <sub>R</sub>	T <sub>J</sub> = 25°C	T <sub>J</sub> = 100°C	μΑ
$(V_R = 40 \text{ V})$ $(V_R = 20 \text{ V})$		20 10	13,000 5,000	

- 1. Mounted with minimum recommended pad size, PC Board FR4.
- 2. 1 inch square pad size (1 X 0.5 inch for each lead) on FR4 board. 3. Pulse Test: Pulse Width  $\leq$  250  $\mu$ s, Duty Cycle  $\leq$  2.0%.

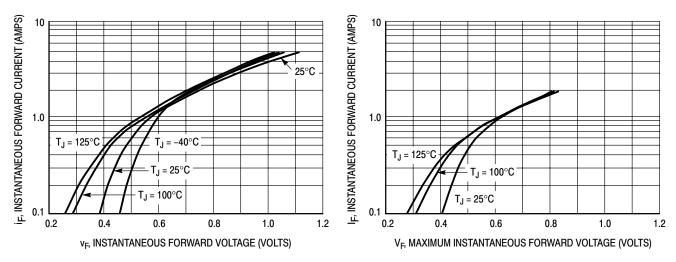
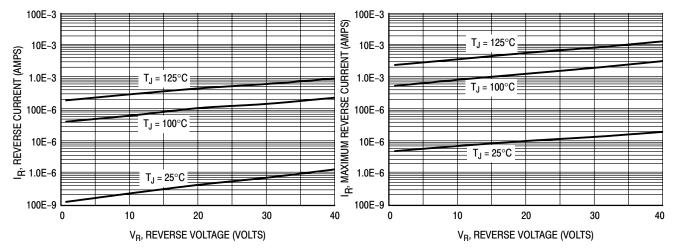


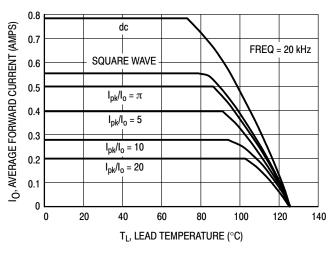
Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



**Figure 3. Typical Reverse Current** 

**Figure 4. Maximum Reverse Current** 



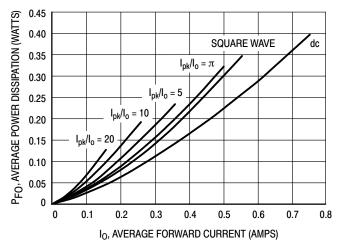
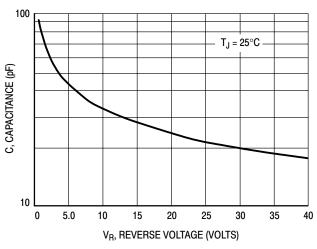


Figure 5. Current Derating

Figure 6. Forward Power Dissipation



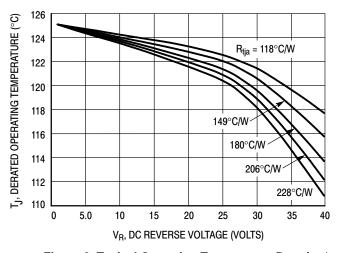


Figure 7. Capacitance

Figure 8. Typical Operating Temperature Derating\*

r(t) = thermal impedance under given conditions,

Pf = forward power dissipation, and

Pr = reverse power dissipation

This graph displays the derated allowable  $T_J$  due to reverse bias under DC conditions only and is calculated as  $T_J = T_{Jmax} - r(t)Pr$ , where r(t) = Rthja. For other power applications further calculations must be performed.

<sup>\*</sup> Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of  $T_J$  therefore must include forward and reverse power effects. The allowable operating  $T_J$  may be calculated from the equation:  $T_J = T_{Jmax} - r(t)(Pf + Pr)$  where

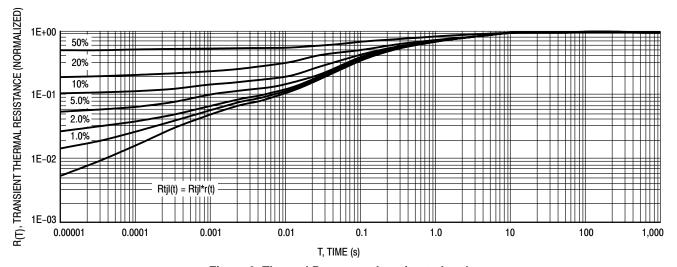


Figure 9. Thermal Response Junction to Lead

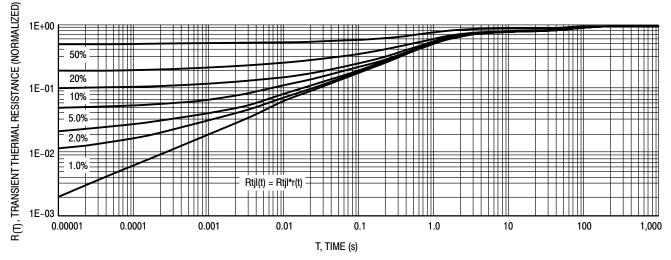
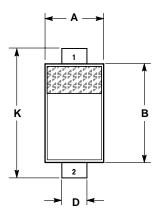
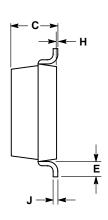


Figure 10. Thermal Response Junction to Ambient

#### **PACKAGE DIMENSIONS**

SOD-123 PLASTIC CASE 425-04 ISSUE C





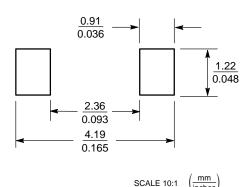
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.055	0.071	1.40	1.80
В	0.100	0.112	2.55	2.85
С	0.037	0.053	0.95	1.35
D	0.020	0.028	0.50	0.70
Е	0.004		0.25	
Н	0.000	0.004	0.00	0.10
J		0.006		0.15
K	0.140	0.152	3.55	3.85

STYLE 1: PIN 1. CATHODE 2. ANODE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free LISA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.